



Product Change Notification

Change Notification #: 117034 - 00
Change Title: Intel® RAID Adapter RSP3GD016J, PCN 117034-00, Product Design, Resistor change and firmware update
Date of Publication: June 27, 2019

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

| | |
|--|---------------|
| Date Customer Must be Ready to Receive Post-Conversion Material*: | July 12, 2019 |
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel

Description of Change to the Customer:

Intel is implementing the following changes on the Intel® RAID Adapters RSP3GD016J:

1. Change in resistor placement in the memory voltage regulator circuit order to allow 1.8V NOR flash memory. This is to allow a second source memory vendor.
2. Update the firmware to version 06.00.10.00 (PH 6 on firmware package 06.00.10.01)

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from this change. Customers may need to validate the function and feature change once the post-change system is available.

Products Affected / Intel Ordering Codes:

| Product Code | MM# | Pre Change TA | Pre Change PBA | Post Change TA | Post Change PBA |
|--------------|--------|---------------|----------------|----------------|-----------------|
| RSP3GD016J | 954492 | J40737-002 | J40738-201 | J40737-003 | J40738-202 |

PCN Revision History:

| | | |
|--------------------------|-------------------------|--------------------------|
| Date of Revision: | Revision Number: | Reason: |
| June 27, 2019 | 00 | Originally Published PCN |



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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